



News Release

Kuala Lumpur 12 September 2018 Today Unisem (M) Berhad ("**Unisem**" or "**the Company**") announced the receipt of a notice together with a pre-conditional announcement ("**Pre-Conditional Offer Announcement**") in relation to the voluntary conditional take-over offer to be undertaken by Huatian Electronics Group (HK) Limited and Huatian Technology (Malaysia) Sdn Bhd ("**HT Malaysia**") (collectively referred to as "**Chinese Offerors**") and Mr John Chia Sin Tet, Mr Alexander Chia Jhet-Wern, Jayvest Holdings Sdn Bhd and SCQ Industries Sdn Bhd (formerly known as SCQ Industries Berhad) (collectively referred to as "**Malaysian Offerors**") ("**Joint Offerors**") that upon satisfaction of all the pre-conditions stipulated in Section 2 of the Pre-Conditional Offer Announcement ("**Pre-Conditions**"), to acquire all the issued shares in the Company, not already held by the Joint Offerors ("**Offer Shares**"), in accordance with the Rules on Take-Overs, Mergers and Compulsory Acquisitions ("**Offer**") ("**Proposed VGO**"). The Offer is conditional upon fulfilment of the Pre-Conditions. Please refer to the attached Pre-Conditional Offer Announcement for further details.

Under the Proposed VGO, all Offer Shares tendered will be acquired by HT Malaysia. Upon completion of the Proposed VGO, it is intended that HT Malaysia, will be the single largest shareholder of Unisem. Mr John Chia (together with other Malaysian Offerors) will retain their existing shareholding of approximately 24.28%.

In connection with the Proposed VGO, Tianshui Huatian Technology Co., Ltd. ("**TSHT**") and the Malaysian Offerors entered into a Collaboration Agreement on 12 September 2018 which sets out the mutually agreed rights, duties, liabilities and obligations of the parties vis-à-vis each other in relation to the Proposed VGO, and their dealings in respect of the affairs of Unisem upon completion of the Proposed VGO. It is an express term of the Collaboration Agreement that there will be no change in management of the Unisem Group.

Mr John Chia, Chairman and Group Managing Director of Unisem, said, "TSHT having a significant presence in the semiconductor industry in the People's Republic of China ("**PRC**") and amongst the largest outsourced semiconductor assembly and test players worldwide would enable Unisem Group to expand more rapidly in its operations in Chengdu, PRC. TSHT has considerable resources and will be better placed to assist Unisem to expand in its other operations than other less strategic partners / shareholders."

About Unisem

Unisem is a global provider of semiconductor assembly and test (OSAT) services for many of the world's most successful electronics companies. We offer an integrated suite of packaging and test services such as wafer bumping, wafer probing, wafer grinding; a wide range of leadframe and substrate IC packaging; wafer level CSP; and RF, analog, digital, and mixed signal test. Our turnkey services include design, assembly, test, failure analysis, and electrical, mechanical, and thermal characterization and modeling. The Company has factory locations in Ipoh, Malaysia; Chengdu, People's Republic of China and Batam, Indonesia. Unisem is listed on the Bursa Malaysia Securities Berhad.

About TSHT

TSHT was incorporated in China on 25 December 2003, and is listed on Shenzhen Stock Exchange. TSHT has been growing continuously and rapidly for years through technological innovation, enhancement of internal management and other measures, which makes TSHT the second largest packaging and test enterprises in China. TSHT provides comprehensive assembly and test services to its customers with application across computers, communications, consumer electronics, Internet of Things, industrial automations and automotive electronics areas.